

664-LF w/green mold compound summary material content, BI Technologies Corp.

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No items are banned per E.U. RoHS. Prepared by Eric Arnold (714) 447-2565

Average mass of 664-x Thin Film network is 0.077 grams each. Scientific notation is used for all component masses.

Material name	also known as	CAS #	Weight per unit (grams)	Special classification
Ag	silver	7440-22-4	1.28E-03	
Al ₂ O ₃	aluminum oxide, alumina	1344-28-1	4.17E-03	
Au	gold	7440-57-5	7.41E-05	
BCB	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	6.88E-06	
carbon black	lamp black, acetylene black	1333-86-4	2.08E-04	
CaO	calcium oxide, quicklime	1305-78-8	1.05E-06	
Cu	copper	7440-50-8	2.78E-02	
epoxy curing agent		trade secret	1.36E-05	
epoxy resin		trade secret	1.23E-04	
epoxy resin, cresol novolac		29690-82-2	8.32E-04	
Fe	iron	7439-89-6	6.70E-04	
FeO ₂	iron (III) oxide, ferric oxide	1345-25-1	2.09E-06	
MgO	magnesium oxide	1309-48-4	1.05E-06	
MnO ₂	manganese dioxide or oxide	1313-13-9	4.19E-06	
Ni	nickel	7440-02-0	3.36E-07	
NiCrOx	nichrome	combination of 7440-02-0, 7440-47-3, & 1308-38-9	2.15E-07	
P	phosphorous, red or amorphous	7723-14-0	8.56E-06	
SiO ₂ , amorphous	silicon dioxide, silica	7631-86-9	6.28E-06	
SiO ₂ , fused silica	silica glass	60676-86-0	3.64E-02	
Sn	tin	7440-31-5	1.26E-03	
TiO ₂	titanium dioxide, titania	13463-67-7	2.09E-06	
Trade secret		n/a	4.19E-03	Non-hazardous and not regulated
Zn	zinc	7440-66-6	3.43E-05	
		Sum of all components	7.71E-02	